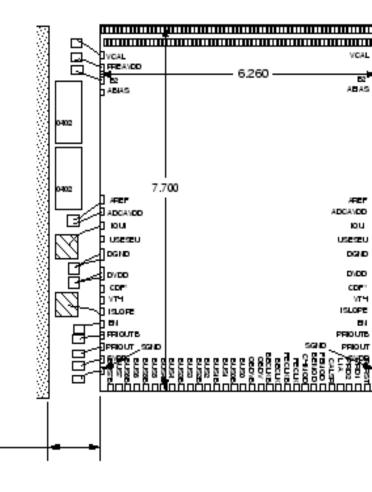
## SVX4 Finger

- SVX4 has side bond pads
  - AVDD & DVDD, DGND
  - AVDD bypass capacitor
  - VCAL
  - One more capacitor necessary for preamp
  - Two resistors to set ADC parameters
  - Priority\_IN and \_OUT, Top/Bottom Neighbor
- Finger between chips allows for bonding
  - 0.5 mm alumina ceramic
  - One (or two) metal layer design
  - 4 surface mounted components
  - Can be simpler if on-chip bypassing works



1.170

## SVX4 Finger

- Checked possibility to bond between chips
  - No finger needed, finger components are integrated on the hybrid
  - Distance between chips 1.37 mm
  - 0.3 mm height dislevel
  - No problems found
  - Ray H. is checking if acceptable for stuffing houses
- Propose to integrate finger with hybrids for L1-5
  - Need to change layouts for L1, L2-5 hybrid
  - 2 capacitors stay between chips, 2 resistors can be moved outside
  - Need to kludge fingers for L1 prototypes

